REMARKS

Applicants wish to express appreciation to Examiner Vikkram Bali for the courtesy of an interview, which was granted to Applicants' representative Sanford T. Colb (Reg. No. 26,856). The interview was held at the USPTO on 26 February 2004. The substance of the interview is set forth in the Interview Summary, numbered Paper No. 8. The present amendment is intended to be fully responsive to all points of rejection raised by the Examiner, and is believed to place the application in condition for allowance.

Claims 8 – 17 are pending in the application. Claims 1 – 7 are cancelled without prejudice or disclaimer.

Claims 8 – 17 are new claims. Claim 8 is an independent claim.

No new matter has been added. Support for the amendments can be found, *inter alia*, in Figs. 2 and 3, and in the written description at: Page 3, line 26 – Page 4, line 14; and Page 5, lines 5 - 12.

Favorable reconsideration and allowance of all claims under consideration is respectfully requested.

Claims Rejections – 35 U.S.C. § 112 (First Paragraph)

Claims 1 – 7 stand rejected under 35 U.S.C. § 112, first paragraph, as failing to comply with the enablement requirement. Claims 1 – 7 have been cancelled thereby obviating this rejection. In view of the foregoing, Applicants, therefore, respectfully request that the Examiner withdraw this rejection.

Claims Rejections – 35 U.S.C. § 112 (Second Paragraph)

Claims 1 – 7 stand rejected under 35 U.S.C. § 112, second paragraph, as

being indefinite for failing to particularly point out and distinctly claim subject matter regarded as the invention. Claims 1 – 7 have been cancelled thereby obviating this rejection. In view of the foregoing, Applicants, therefore, respectfully request that the Examiner withdraw this rejection.

Claims Rejections – 35 U.S.C. § 103(a) – Leung (U.S. 4,778,745)

Claims 1 – 7 stand rejected under 35 U.S.C. 103(a) as being unpatentable over Leung (U.S. 4,778,745). Applicants respectfully traverse the above rejection. Claims 1 – 7 have been cancelled without prejudice or disclaimer.

With respect to new claims 8 – 17, it is noted that Leung describes a defect detection method for semiconductor patterns, namely a method of detecting opaque defects on a reticle used to define die patterns during semiconductor device fabrication.

Claim 8 is a new claim and includes, *inter alia*, the following distinguishing recitation:

> *defining an image map for use in inspecting a plurality of electrical circuits formed on a non-silicon wafer substrate, including:*
>
> > *obtaining at least two different references, each of said at least two references corresponding to one of at least two distinct electrical circuit configurations on said non-silicon wafer substrate;*
> >
> > *obtaining orientation information for said plurality of electrical circuits; and*
> >
> > *utilizing said at least two different references together with said orientation information to define said image map;*
>
> *acquiring an optical inspection output of said plurality of electrical circuits formed on said non-silicon wafer substrate; and*
>
> *employing said image map and said inspection output in a computerized automated inspection system to automatically inspect said plurality of electrical*

circuits.

As noted above, Leung describes a defect detection method for reticles employed in the fabrication of silicon semiconductor wafers. Silicon wafers comprise a plurality of multiple reproduced dies or chips. In accordance with conventional semiconductor fabrication practice, all of the dies and chips on a silicon semiconductor wafer comprise identical electrical circuits, and all dies and chips have the same spatial orientation, albeit a different location. Nothing in Leung even remotely suggests a deviation from this conventional silicon semiconductor wafer fabrication practice.

Leung fails to show or suggest obtaining at least two different references, each reference corresponding to one of at least two distinct electrical circuit configurations on a non-silicon wafer substrate. Moreover, Leung fails to show or suggest obtaining orientation information for a plurality of electrical circuits to be inspected. Additionally, Leung fails to show or suggest utilizing the at least two different references together with the orientation information to define an image map which is used in computerized automated optical inspection.

Nothing in the prior art subject shows or suggests subject matter missing from Leung that renders claim 8 unpatentable

In view of the foregoing, Applicants respectfully submit that claim 8, as submitted, is deemed patentable over Leung. Applicants respectfully request entry and allowance of claim 8.

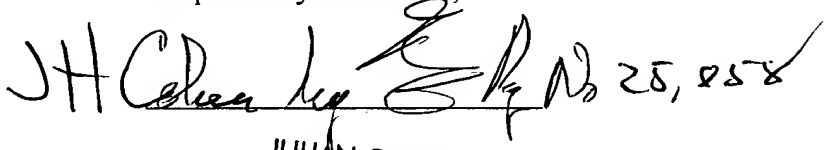
Claims 9 – 17 depend, directly and indirectly, from claim 8. Inasmuch as claim 8 is deemed patentable, Applicants respectfully submit that claims 9 – 17 are also patentable over Leung. Applicants respectfully request entry and allowance of claims 9 - 17.

Conclusion and Request for Interview

In view of the foregoing, this application is believed to be in order. Reconsideration and allowance of this application are respectfully solicited.

If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly invited to contact the undersigned attorney at the telephone number listed below.

Respectfully submitted,



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